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8-21-02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Christo P. Bojkov, et al.

Art Unit: Not Assigned

Serial No.: 10/086,117

Examiner: Not Assigned

Filed: 02/26/02

Docket: TI-33887

For: Waferlevel Method for Direct Bumping on Copper Pads in Integrated Circuits

Assistant Commissioner for
Patents
Washington, D. C. 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)
I hereby certify that the above correspondence is being deposited
with the U.S. Postal Service on 6-5-02
as First Class Mail in an envelope addressed to: Assistant
Commissioner for Patents, Washington, D.C. 20231.

Karen Vertz

Karen Vertz

6-5-02

Date

PRELIMINARY AMENDMENT

Dear Sir:

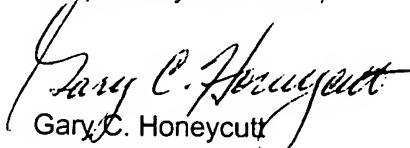
This application claims priority under 35 USC 119 (e)(1) of provisional application number 60/342,949, filed 12/21/01.

Please amend the specification by inserting before the first line the sentence:

--This application claims priority under 35 USC § 119 (e) (1) of provisional application number 60/342,949 filed 12/21/01.--

Should the Examiner have any further comments or suggestions, it is respectfully requested that the Examiner contact the undersigned in order to expeditiously resolve any outstanding issues.

Respectfully submitted,


Gary C. Honeycutt
Reg. No. 20,250
Attorney for Applicants

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